

## IN THE CLAIMS

Please replace the claims as filed with the claims set forth below. This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) An anode for electroplating, which comprises an anode base and a shield, wherein the anode base comprises a support material and an active layer, and wherein the shield is attached to the anode base at a distance from it and reduces material transport to and from the anode base, wherein the shield comprises a conductive metal material or a conductive metal and plastic material and wherein the conductive metal material of the shield is connected to the anode base in an electric current-conducting manner providing an electrostatic barrier.

2. (Previously Presented) The anode according to claim 1, in which the support material is self-passivating under electrolysis conditions.

3. (Previously Presented) The anode according to claim 1, in which the active layer is electron-conducting.

4. (Cancelled)

5. (Cancelled)

6. (Currently Amended) The anode according to claim 5~~1~~, in which the shield comprises at least one of a metal grid, an expanded metal and a perforated plate.

7. (Cancelled)

8. (Cancelled)

9. (Previously Presented) The anode according to claim 1, in which the shield is at a distance of 0.01 to 100 mm from the anode base.

10. (Previously Presented) The anode according to claim 1, in which the form of the shield and the arrangement and the distance of the shield from the anode base are such that the gas bubbles forming at the anode during electroplating are brought together.

11. (Previously Presented) The anode according to claim 1, in which the anode is connected as a cathode.

12. (Previously Presented) A method of electroplating comprising: providing an anode base comprising a support material and an active layer;

providing a shield attached to the anode base at a distance from the anode base; wherein the shield comprises a conductive metal material or a conductive metal and plastic material and wherein the shield is connected to the anode base in an electric current-conducting manner;

applying electrical current to the anode base and shield;

reducing material transport to and from the anode base through the action of the shield as a mechanical barrier; and

reducing material transport to and from the anode base through the action of the shield as an electrostatic barrier.

13.-19. (Cancelled)

20. (Previously Presented) The method of electroplating of claim 12 further comprising providing a support material that is self-passivating under electrolysis conditions.

21. (Previously Presented) The method of electroplating of claim 12 further comprising providing an active layer that is electron conducting.

22. (Cancelled)

23. (Cancelled)

24. (Previously Presented) The method of electroplating of claim 12 further comprising providing a shield comprising at least one of a metal grid, an expanded metal and a perforated plate.

25. (Cancelled)

26. (Cancelled)

27. (Previously Presented) The method of electroplating of claim 12 further comprising attaching the shield to the anode base at a distance of 0.01 to 100 mm.

28. (Previously Presented) The method of electroplating of claim 12 further comprising forming the shield and selecting the distance of the shield from the anode base such that gas bubbles forming at an anode during electroplating are brought together.

29. (Previously Presented) The method of electroplating of claim 12 further comprising applying cathodic current to the anode base.